

Features

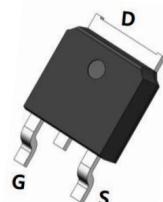
- N-channel SJ MOSFET with deep trench process
- Fast switching speed
- 100% avalanche tested
- Improved dv/dt capability

Application

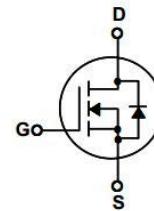
- Switch Mode Power Supply(SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)
- AC-DC Switching Power Supply

Key Performance Parameters

Parameter	Value	Unit
V_{DSS}	650	V
I_D	11	A
R_{DSON}_max	360	mΩ



TO-252



Equivalent Circuit

Table 1. Absolute Maximum Ratings (T_C=25°C unless otherwise specified)

Symbol	Parameter	Value	Units
V _{DSS}	Drain-Source Voltage	650	V
V _{GS}	Gate-Source Voltage	±30	
I _D	Continuous Drain Current (T _C =25°C)	11	A
	Continuous Drain Current (T _C =100°C)	7	
I _{DM}	Pulsed Drain Current	44	
E _{AS}	Single Pulse Avalanche Energy L=10mH, VDS= 50V, RG = 25 Ω , TC=25°C	135	
P _D	Power Dissipation	33	W
dv/dt	Peak Diode Recovery dv/dt	50	V/ns
T _L , T _{PKG}	Maximum Temperature for Soldering	300	°C
	Leads at 0.063in(1.6mm)from Case for 10 seconds Package Body for 10 seconds	260	
T _J , T _{STG}	Operating Junction Storage Temperature Range	-55 to +150	



FTK65T360D

Table 2. Thermal Characteristic

Symbol	Parameter	Value	Units
$R_{\Theta JA}$	Junction-to-Ambient	62	°C/ W
$R_{\Theta JC}$	Junction-to-Case	3.79	°C/ W

Table 3. Electrical Characteristics ($T_J=25^\circ C$ unless otherwise specified)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off Characteristics						
BVDSS	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	650	--	--	V
$V_{GS(th)}$	Gate-Source Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	2.2	3.2	4.2	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 650 V, V_{GS} = 0 V$	--	--	1	μA
I_{GSS}	Gate- to- Source Forward Leakage	$V_{DS} = 0 V, V_{GS} = 30V$	--	--	100	nA
	Gate- to- Source Reverse Leakage	$V_{DS} = 0 V, V_{GS} = -30V$	-100	--	--	
$R_{DS(ON)}$	Drain-Source On-State Resistance	$V_{GS} = 10V, I_D = 5.5A$	--	281	360	$m\Omega$
Dynamic Characteristics						
Ciss	Input Capacitance	$V_{GS} = 0V, V_{DS} = 50V, f = 1.0MHz$	--	574	--	pF
Coss	Output Capacitance		--	45	--	
Crss	Reverse Transfer Capacitance		--	5.5	--	
Q_g	Total Gate Charge	$I_D = 5.5A, V_{DS}=400V$ $V_{GS} = 10V$	--	17.5	--	nC
Q_{gs}	Gate-Source Charge		--	4.7	--	
Q_{gd}	Gate-Drain Charge		--	8.5	--	
Resistive Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS} = 400 V, I_D = 5.5 A$ $R_g = 25 \Omega$	--	25	--	ns
t_r	Turn-on Rise Time		--	44	--	
$t_{d(off)}$	Turn-off Delay Time		--	64.5	--	
t_f	Turn-off Fall Time		--	23	--	
Source-Drain Diode Characteristics						
V_{SD}	Body Diode Forward Voltage	$I_S = 5.5A, V_{GS}=0V$	--	--	1.4	V
I_S	Continuous Diode Forward Current	Integral pn- diode in MOSFET	--	--	11	A
I_{SM}	Pulse diode forward current		--	--	44	
t_{rr}	Reverse Recovery Time	$I_S = 5.5A, dI/dt = 100A/\mu s,$ $V_R=400V$	--	235	--	ns
Q_{rr}	Reverse Recovery Charge		--	2.3	--	nC

Typical Electrical and Thermal Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise noted)

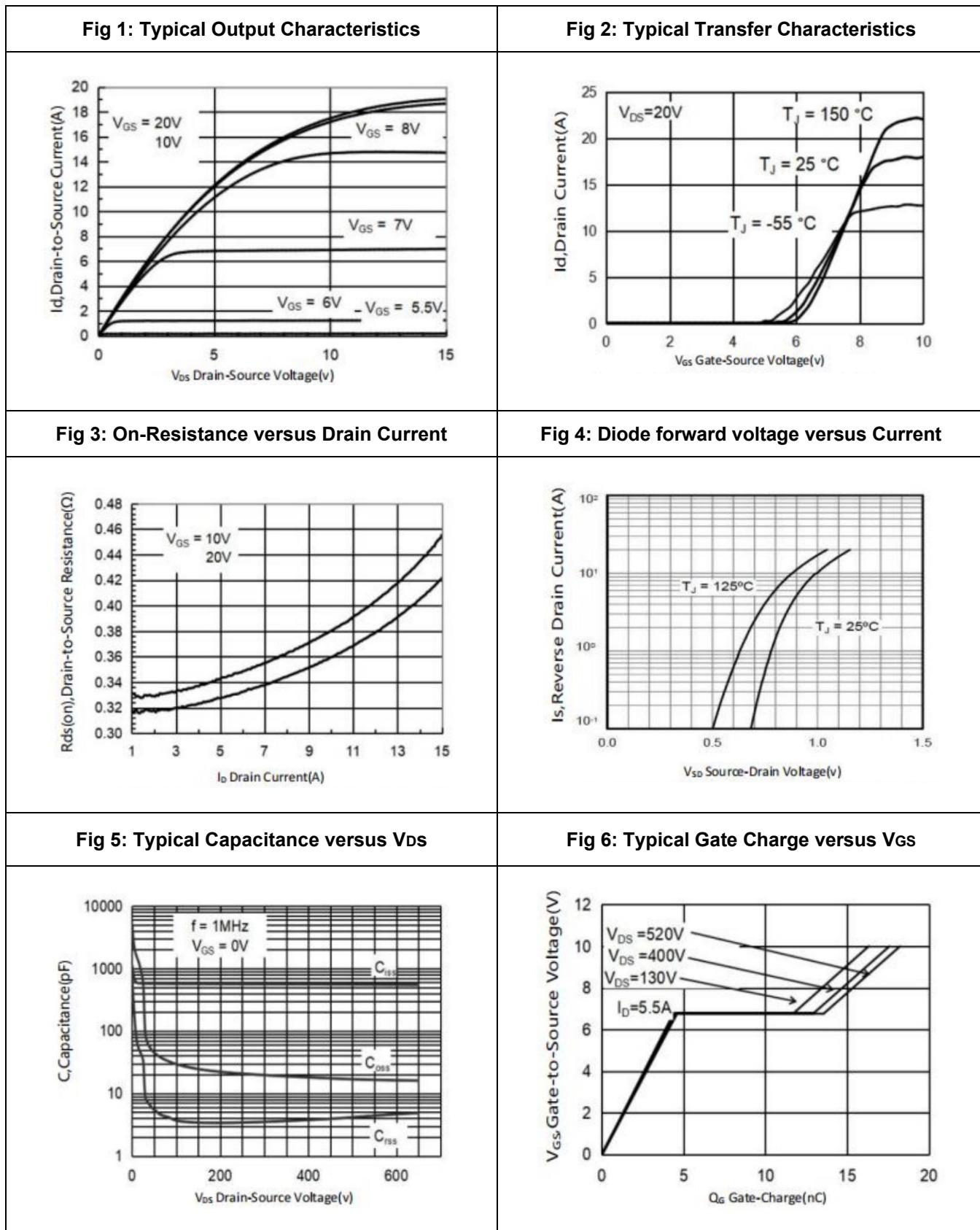


Fig 7: BV_{DSS} Variation with Temperature

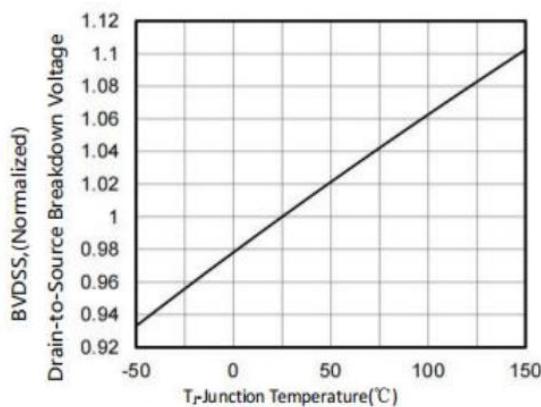
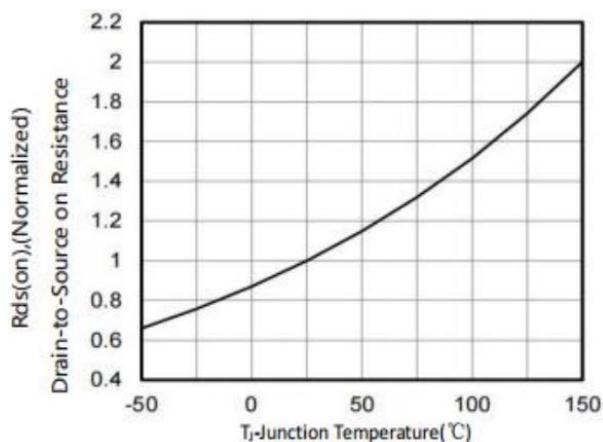
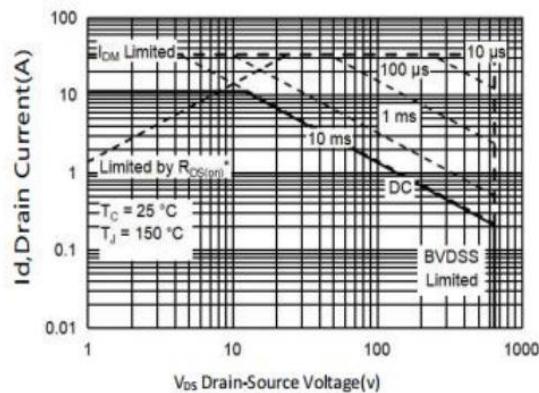


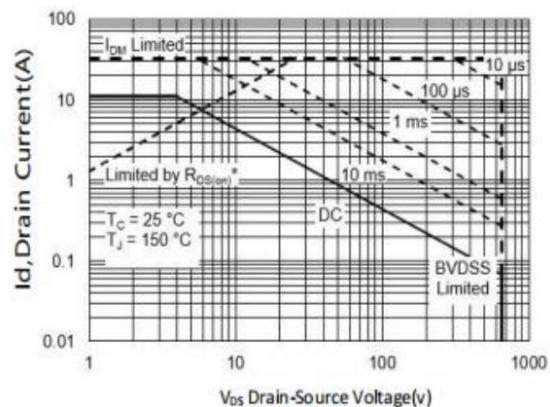
Fig 8: On-Resistance Variation with Temperature



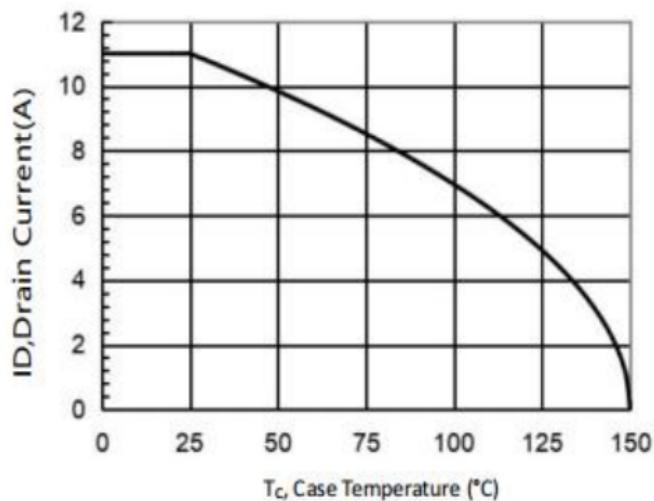
**Fig 9: Maximum Safe Operating Area
TO-252**



**Fig 10: Maximum Safe Operating Area
TO-220F**



**Fig 10: Maximum Continuous Drain Current
versus Case Temperature**



Test Circuit and Waveforms

Fig A: Gate Charge Test Circuit & Waveforms

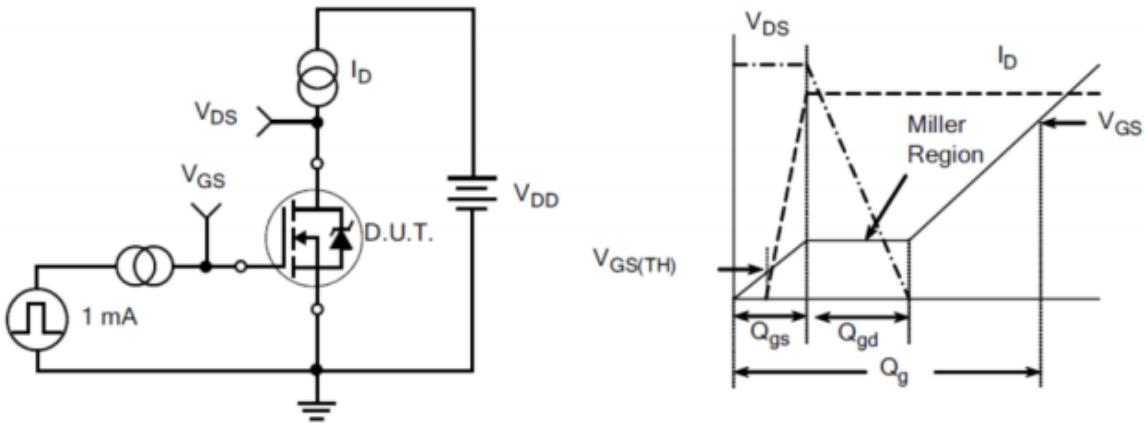


Fig B: Resistive Switching Test Circuit & Waveforms

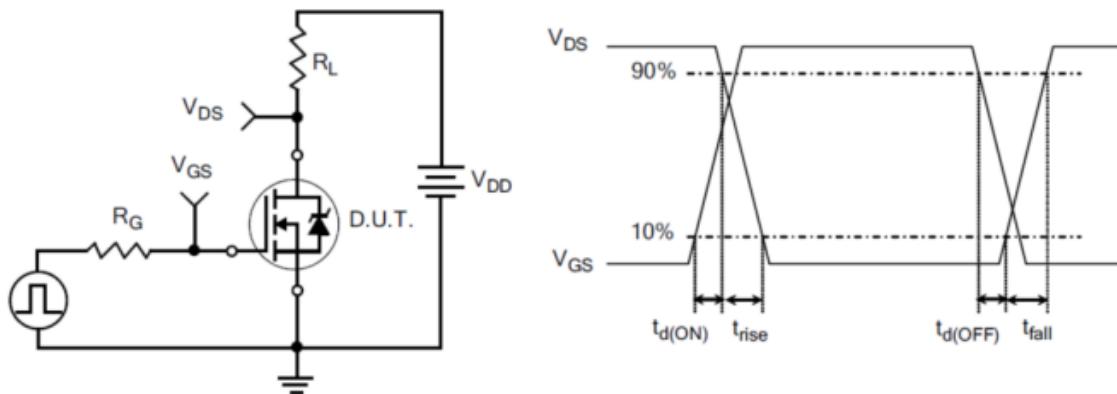


Fig C: Unclamped Inductive Switching Test Circuit & Waveforms

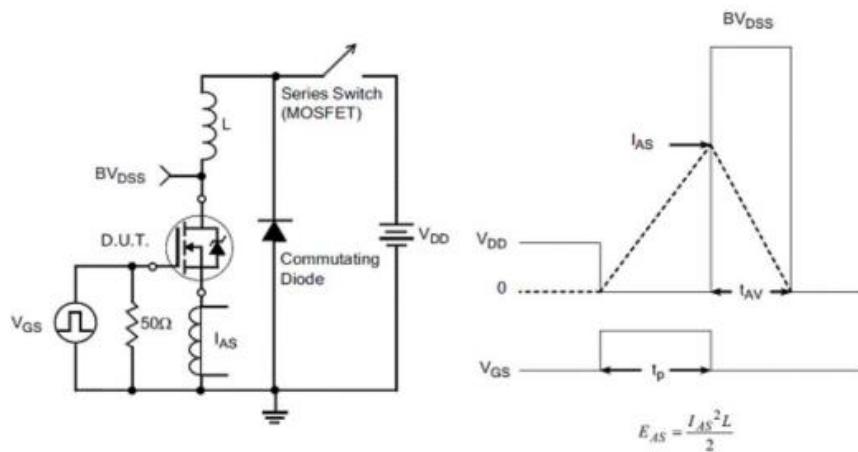
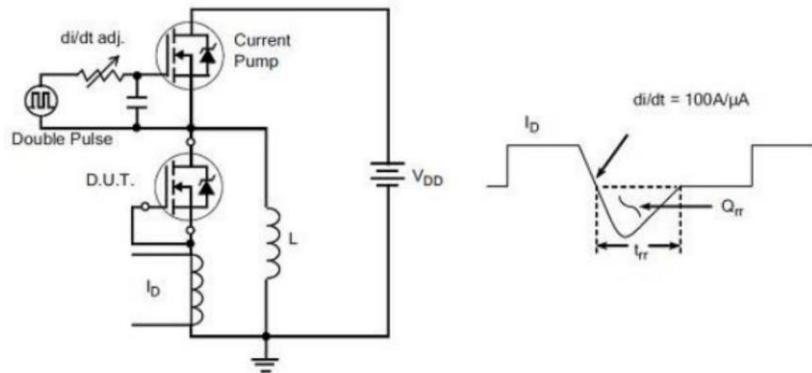
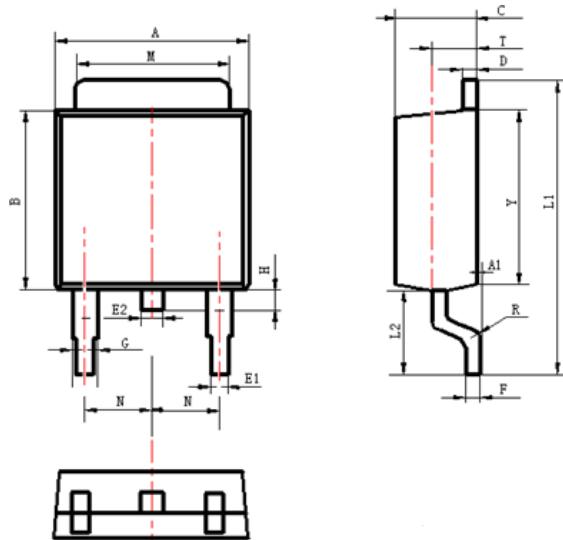


Fig D: Diode Reverse Recovery Test Circuit & Waveforms



Package Information

TO-252



Items	Values(mm)	
	MIN	MAX
A	6.30	6.90
A1	0	0.16
B	5.70	6.30
C	2.10	2.50
D	0.30	0.70
E1	0.60	0.90
E2	0.70	1.00
F	0.30	0.60
G	0.70	1.20
L1	9.60	10.50
L2	2.70	3.10
H	0.40	1.00
M	5.10	5.50
N	2.09	2.49
R	0.3	
T	1.40	1.60
Y	5.10	6.30